

*Advancing GaN Power ICs with
Efficiency, Reliability & Autonomy*



Navitas

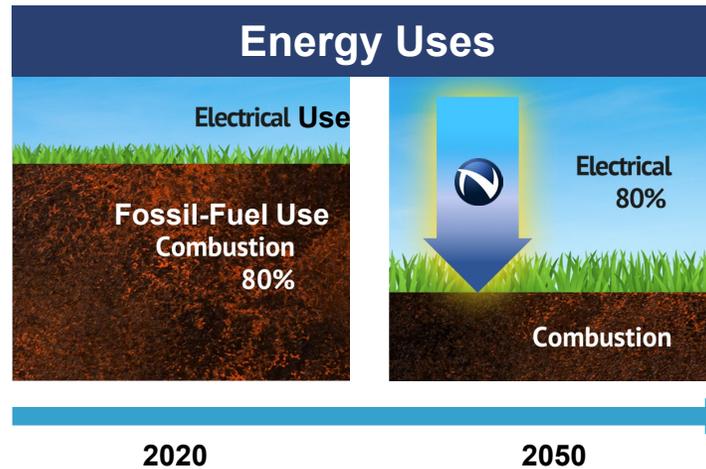
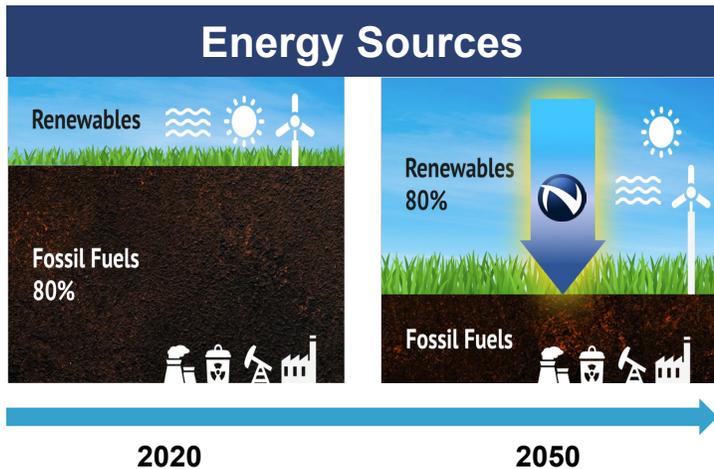
Energy • Efficiency • Sustainability



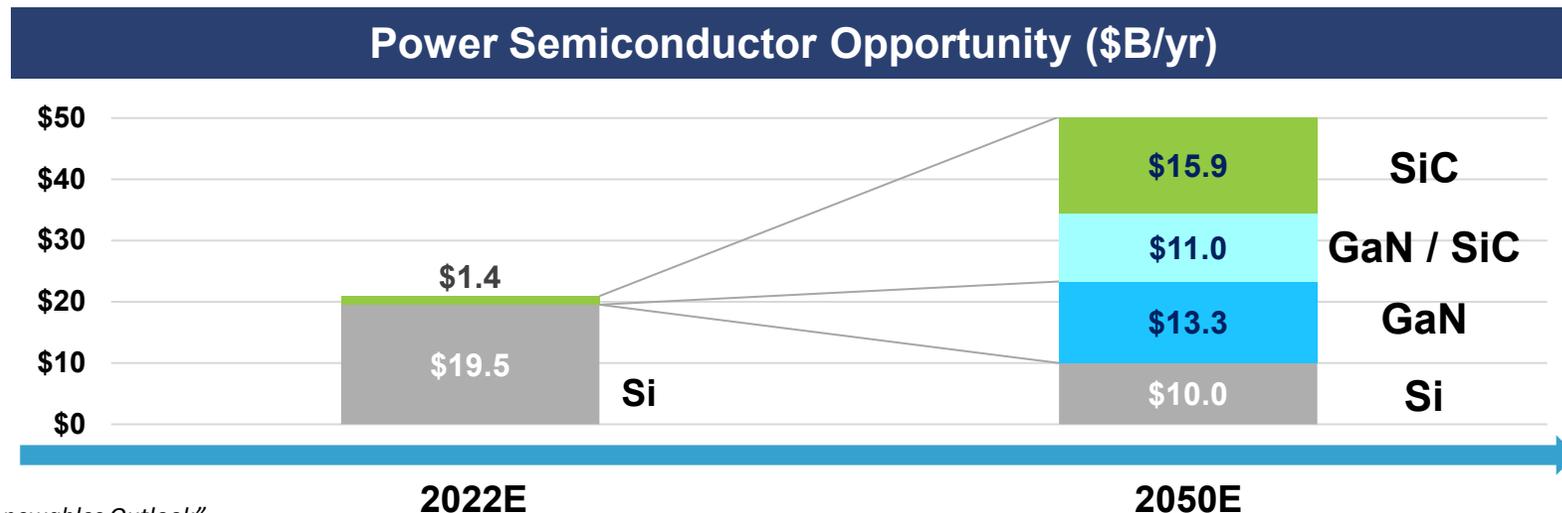
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EPE'22 ECCE Europe-Conference, 7th September 2022

Energy sources and uses are being electrified...

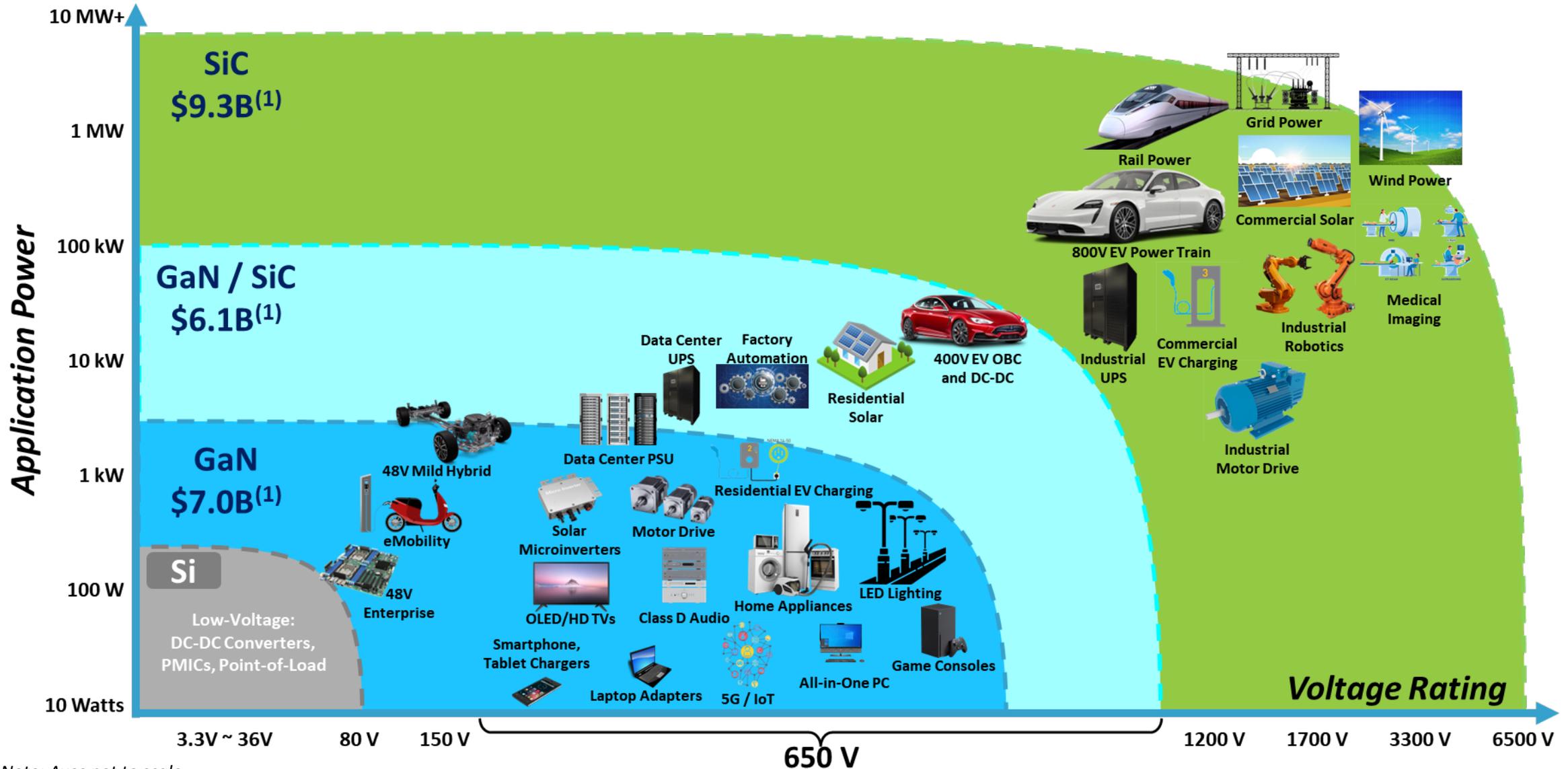


...creating a **\$40B GaN + SiC opportunity by 2050**



Fossil-fuel vs renewable ratios adapted from IRENA 2020 "Global Renewables Outlook".
 Shift required to meet "Transforming Energy Scenario, 9.5 Gton target in 2050", per Paris Agreement's 1.5°C rise.
 Market opportunity \$ from Yole Développement, 2020 and Navitas analysis.

GaN + SiC: The Future of Power Semis



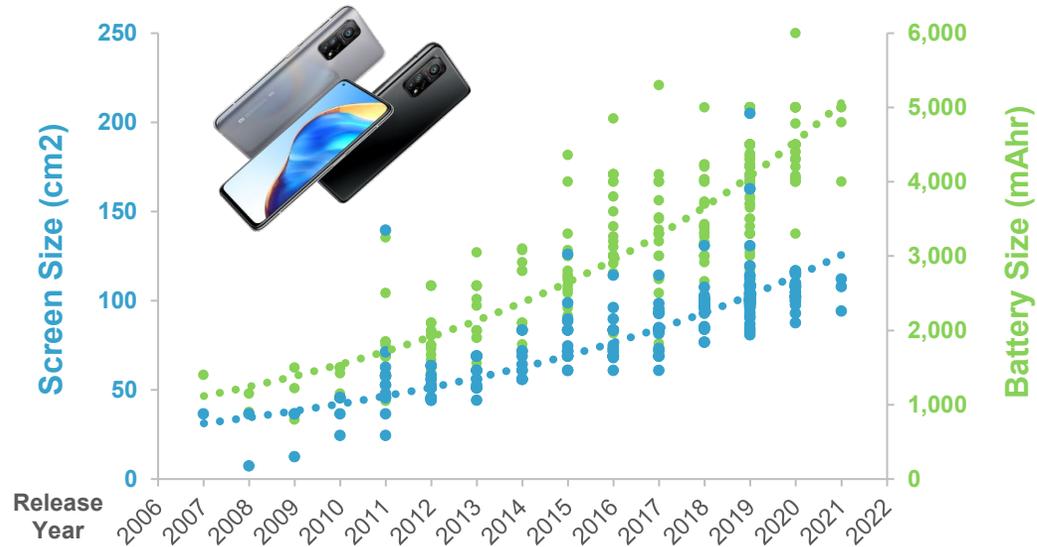
Note: Axes not to scale

Note (1): 2026E potential, Source: Yole, DNV, IRENA, Fraunhofer ISE, IHS, Cisco, Hyperscale, Peer annual reports, Wall Street research.

GaN is Positioned To Be The Future Of Mobile Charging

Larger Mobile Screens And Batteries Need More Power

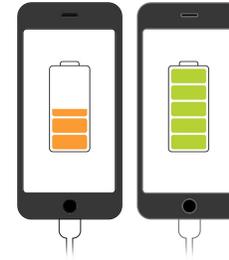
Screen Size and Battery Size Continue to Increase⁽¹⁾



Over \$2.5B GaN IC opportunity⁽³⁾

- 2.5Bu per year of mobile wall chargers shipped
 - Phone, tablet, laptop and after-market
- Over \$1 of GaN content per charger and increasing over time

Fast
Up to 3x more power
Up to 3x faster charging



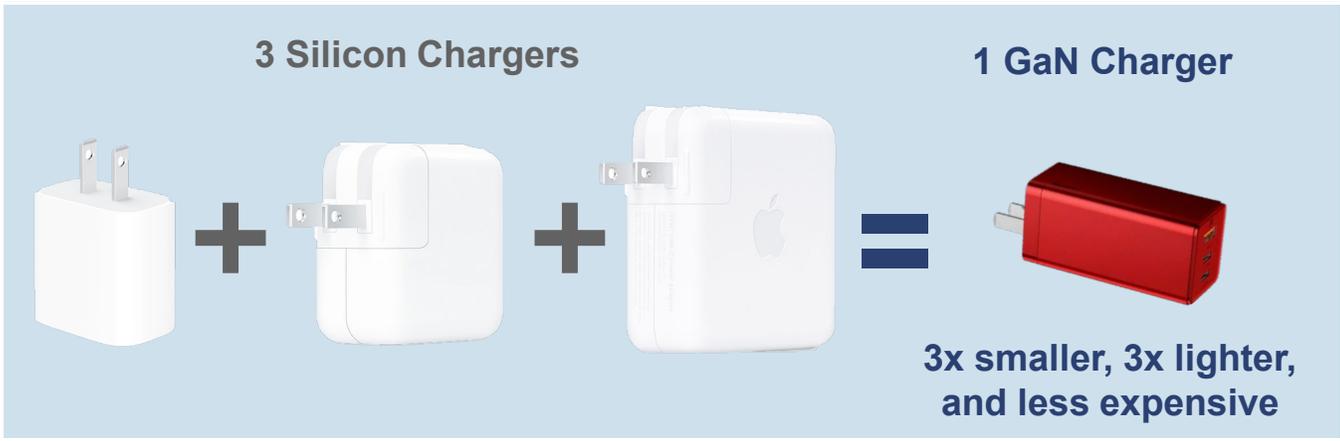
Mobile
Half the size and weight
of traditional chargers



Universal
One charger for **ALL** your devices
One and Done!!



65W Multi-Port GaN Wall Charger⁽²⁾

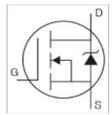


Mobile is Moving to GaN Fast Chargers, Creating a Multi-Billion Dollar GaN IC Opportunity

1) Includes Huawei, Xiaomi, OPPO, OnePlus, Realme, Samsung, Apple and Google.
 2) Based on Navitas measurements of select GaN-based mobile wall chargers compared to Si-based chargers with similar output power.
 3) Based on estimates from IDC PC Tracker, USB-C research, Yole Research and Navitas estimates.

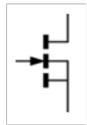
The GaN Revolution

Silicon FET



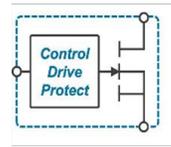
- Old, slow
- High Qg
- High Coss
- Fsw < 100kHz

Discrete GaN



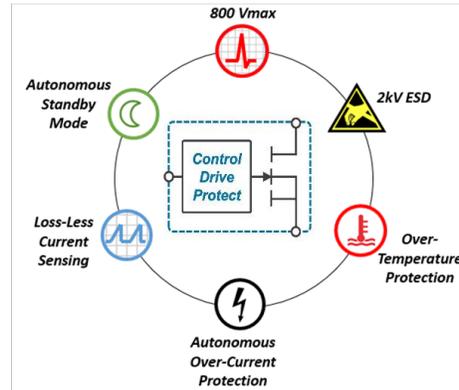
- Exposed gate
- External gate drive
- dV/dt sensitivity
- Layout sensitivity
- ESD sensitivity
- Unknown reliability
- Unknown robustness

GaNFast™



- ✓ Internal Gate
- ✓ Integrated Gate Drive
- ✓ dV/dt Immunity
- ✓ Layout Insensitive
- ✓ 2KV ESD rating
- ✓ Proven Reliability
- ✓ Proven Robustness

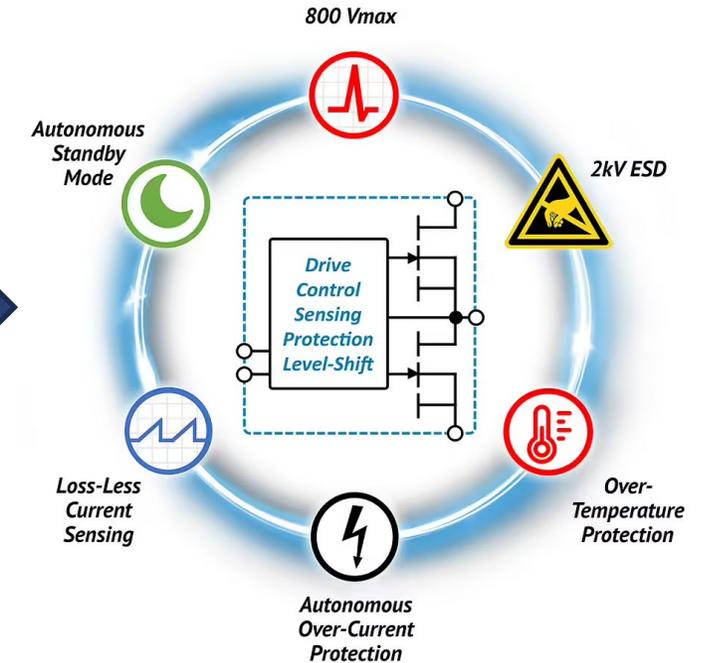
GaNSense™



GaNFast benefits plus:

- ✓ Autonomous Standby
- ✓ Autonomous Protection
- ✓ Loss-less Current Sensing
- ✓ High Precision
- ✓ High Efficiency

GaNSense Half-Bridge



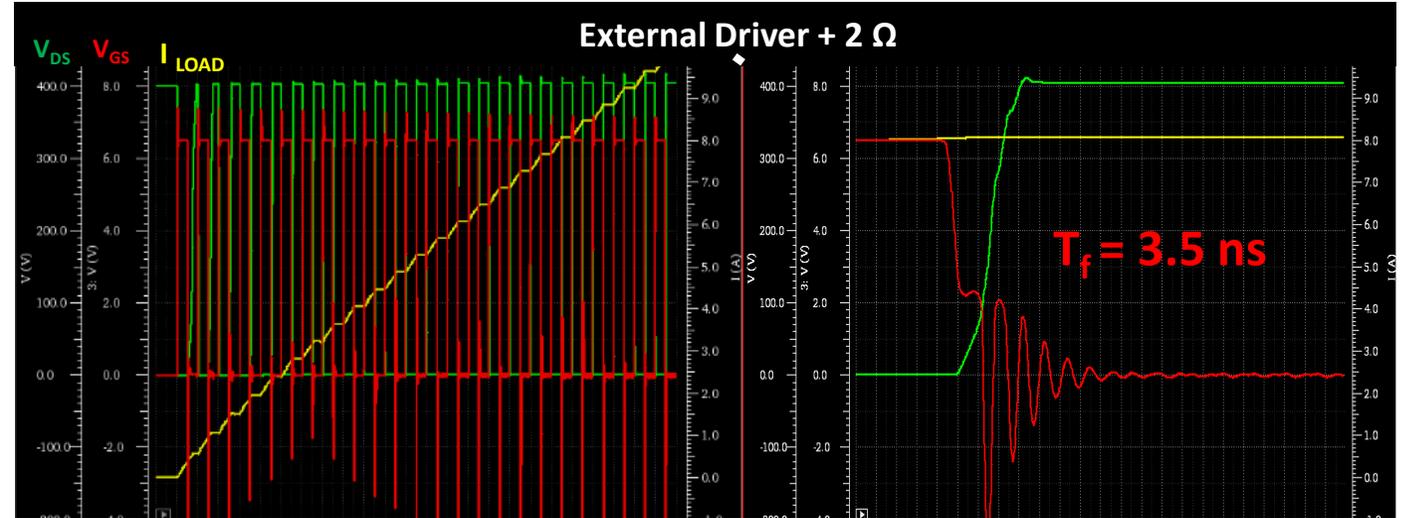
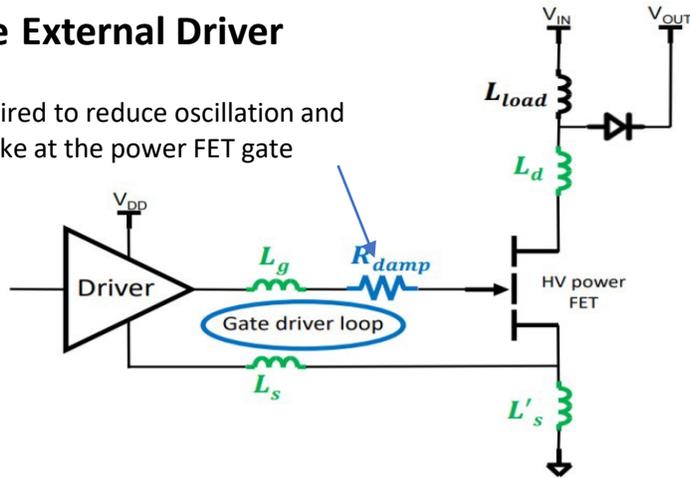
GaNSense Singles benefits plus:

- ✓ Highest integration
 - ✓ integrated HS and LS FETs & level-shift isolation
 - ✓ integrated HS boot-strap
 - ✓ Shoot-through protection
 - ✓ Enlarged cooling pads
- ✓ Fastest switching
- ✓ Highest efficiency

GaN Integration for Efficiency, Speed & Stability

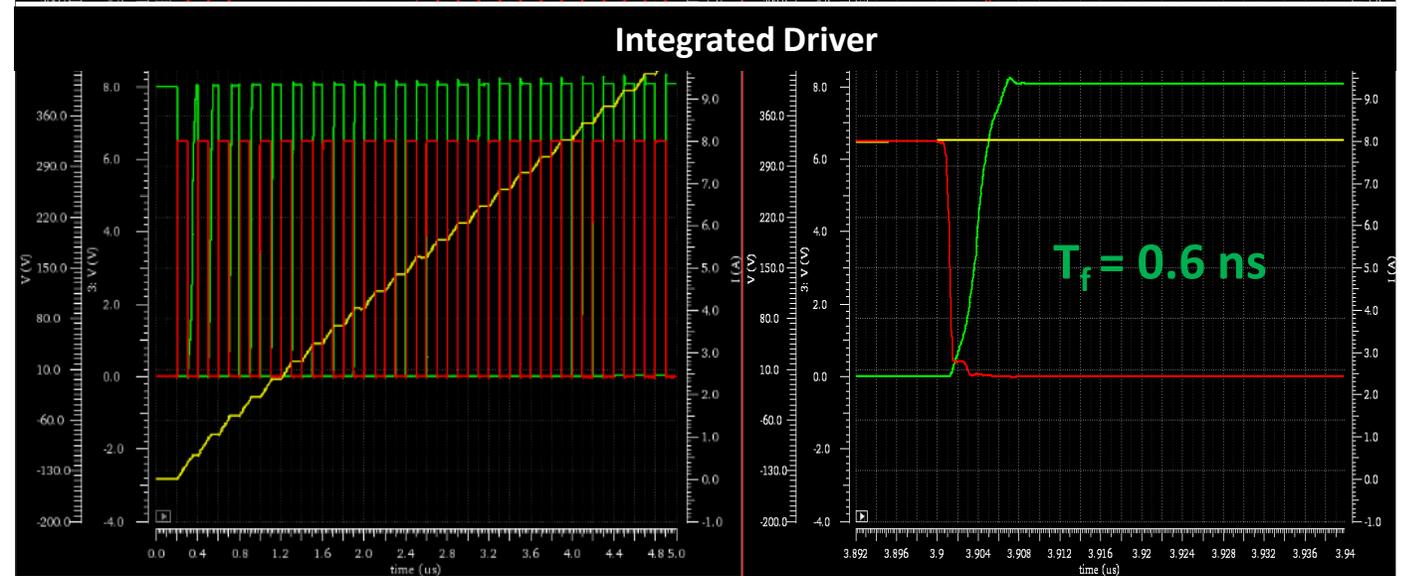
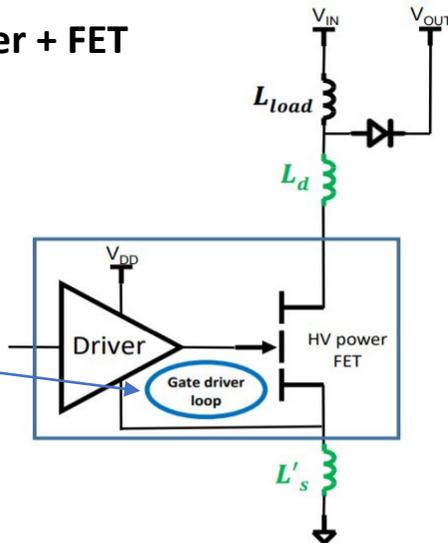
Discrete External Driver

R_{DAMP} required to reduce oscillation and voltage spike at the power FET gate



Monolithic GaN Driver + FET

Minimized gate loop eliminates any unwanted noise to effect the control and reliability of the device



GaN Integration Drives Performance

Discrete GaN Half-Bridge

- × 33 components
- × 250 mm² footprint
- × External HB driver HVIC
- × External. HV bootstrap
- × 2x HV bypass diodes
- × 2x external gate drives
- × Exposed gates



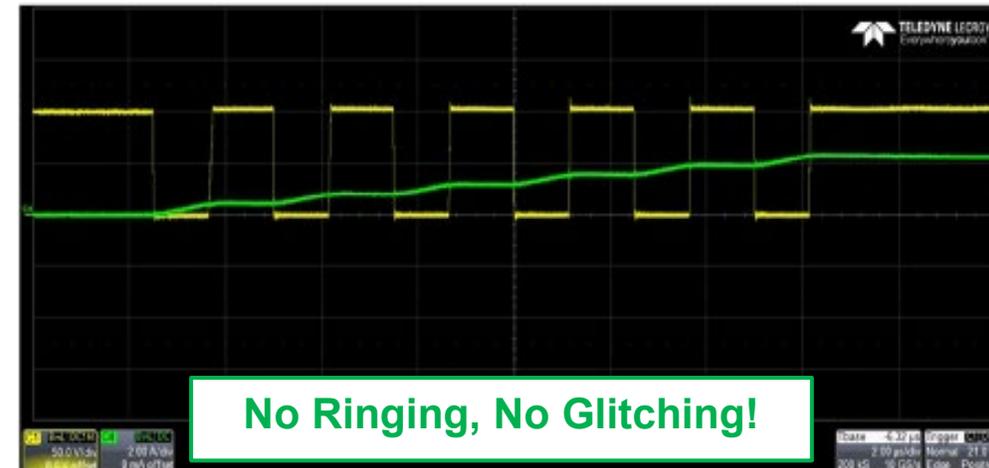
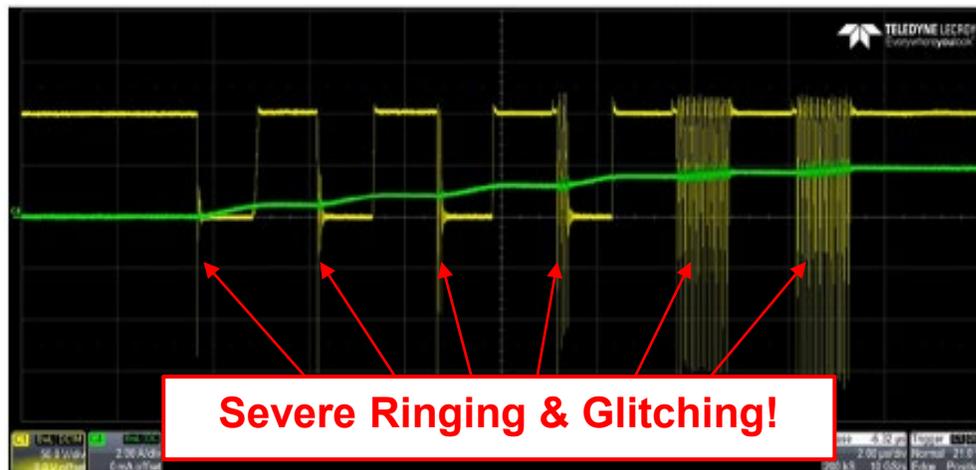
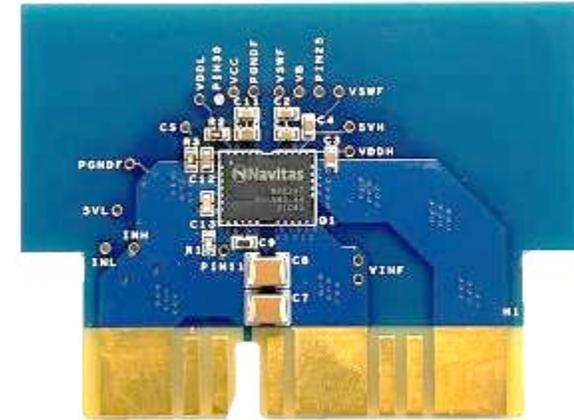
61% fewer components

64% smaller footprint

Complete integration

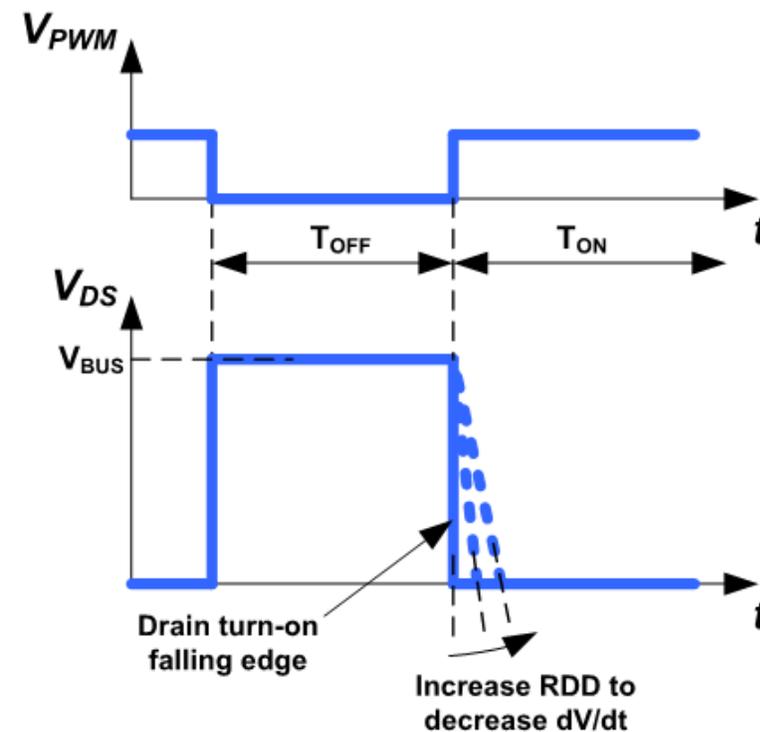
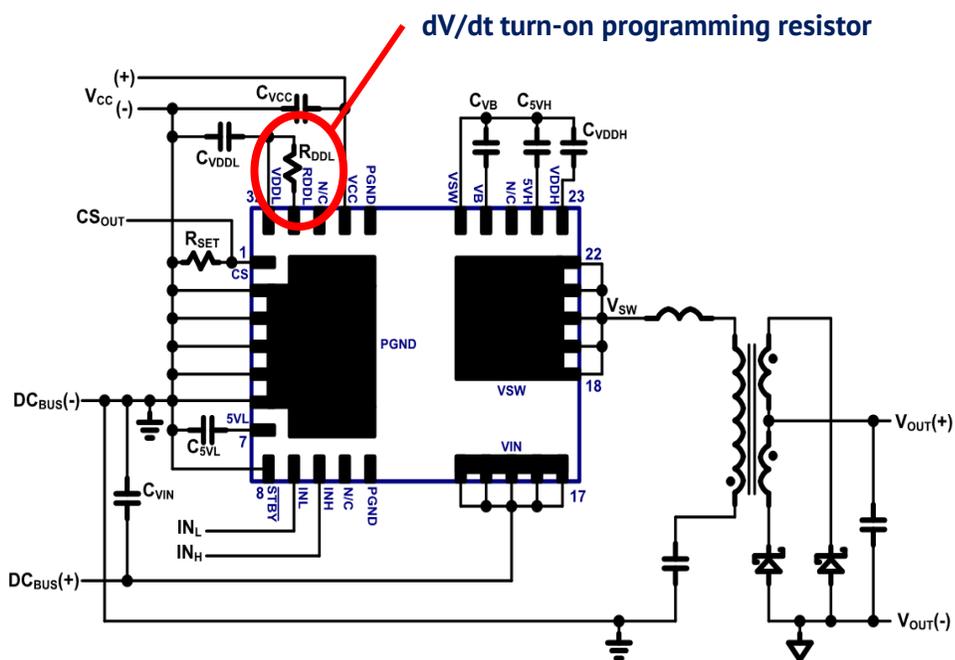
GaNSense Half-Bridge IC

- ✓ 13 components
- ✓ 90 mm² footprint
- ✓ Level shifters
- ✓ Bootstrap
- ✓ Gate drivers
- ✓ No exposed gates

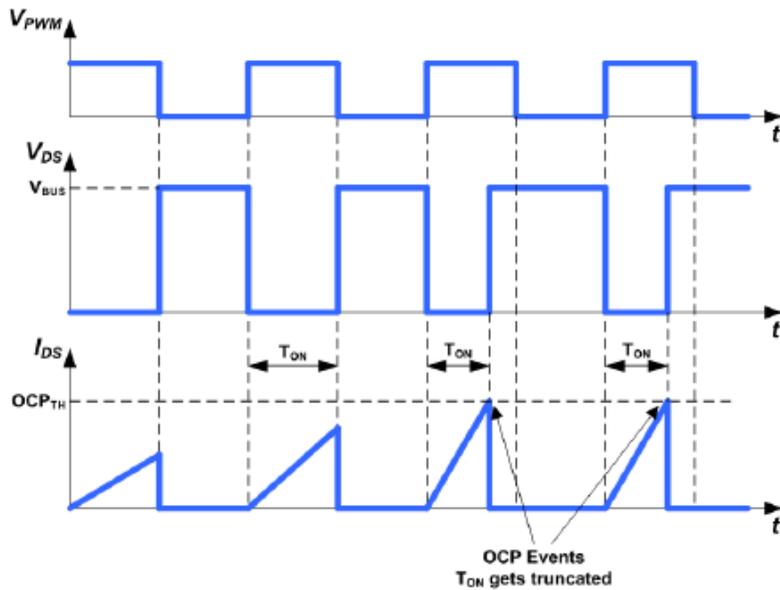


Programmable Turn-on dV/dt Control

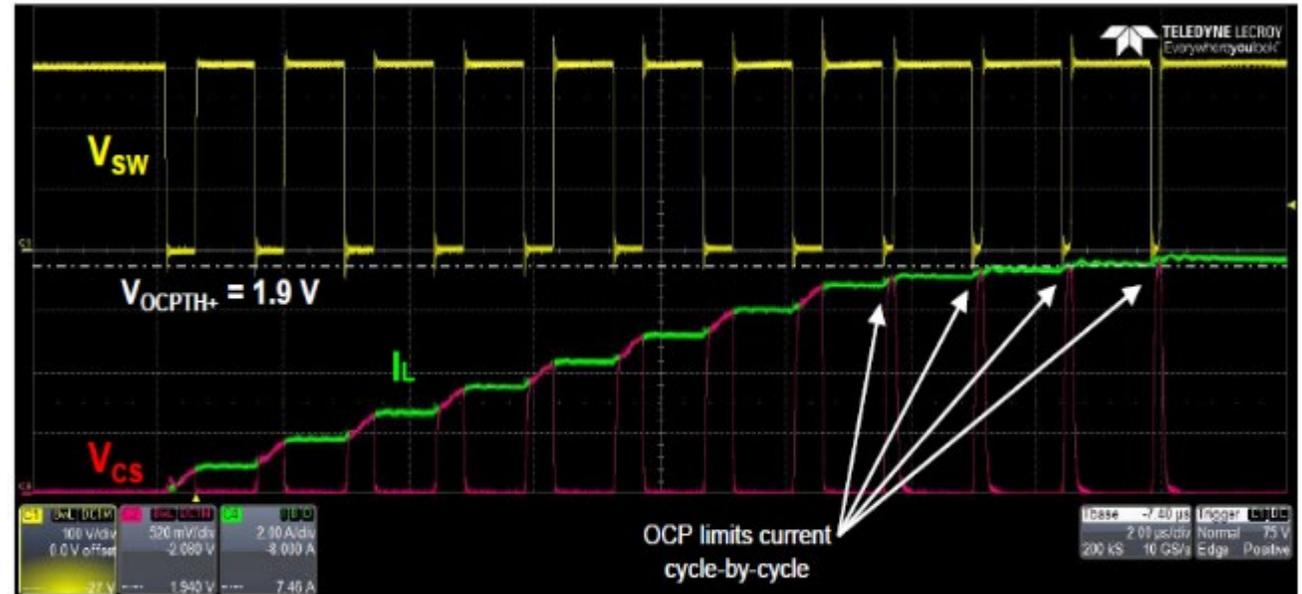
- Limits the slew rate (dV/dt) of the drain of the power FET during turn-on
- First start-up pulses or during hard-switching conditions
- Reduce EMI or reduce circuit switching noise



Cycle-by-Cycle Over-Current Protection (OCP)



Over-Current Protection DCM Timing Diagram

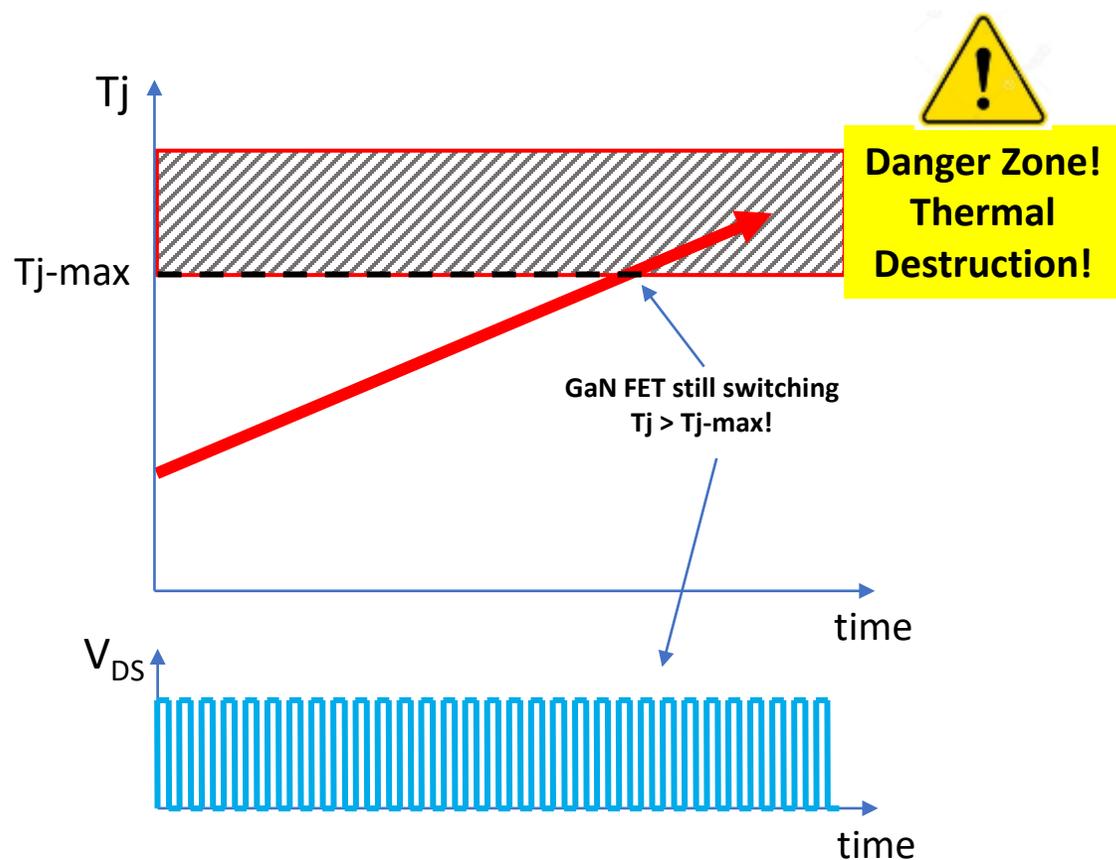


Cycle-by-cycle over current protection in CCM boost configuration

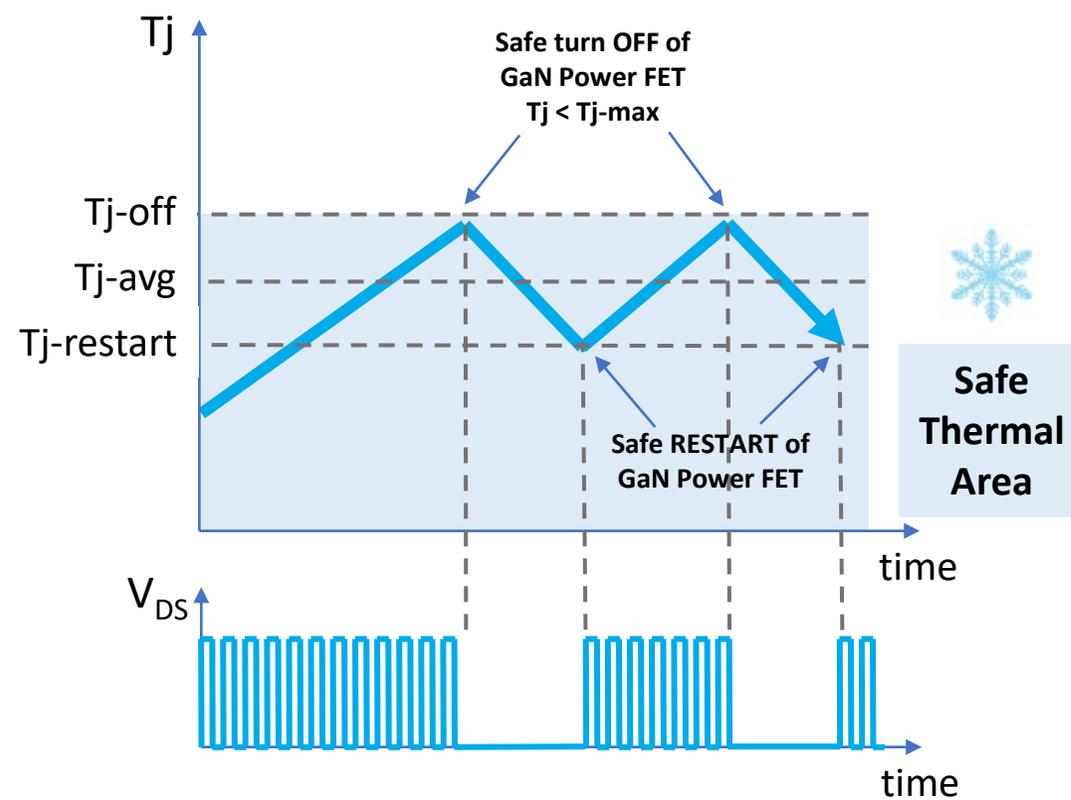
- If $V_{CS} > 1.9V$, internal gate driver will turn off the GaN IC, ending the on-time
 - **OCP response 'detect-to-protect' in 30 ns!** 6x faster than conventional controllers
- Accurate, user-programmable current set-point (based on $I_{DRAIN} \rightarrow I_{CS}$ ratio, R_{SET})
- Turn-on OCP blanking time prevents noise from triggering the fault, is optimized for protection

Over-Temperature Protection (OTP)

Discrete GaN



GaN Sense IC w/OTP



Soft Switching & GaN ICs = High Efficiency & Frequency

Primary Switch Power Loss using Silicon FETs:

$$P_{FET} = P_{COND} * k + P_{DIODE} + P_{T-ON} + P_{T-OFF} + P_{DR} + P_{QRR} + P_{QOSS}$$

P_{COND} → $R_{DS(ON)}$ loss
 k → Duty cycle loss
 P_{DIODE} → Reverse conduction loss
 P_{T-ON} → Switch-ON transition loss
 P_{T-OFF} → Switch-OFF transition loss
 P_{DR} → Gate Drive loss
 P_{QRR} → Reverse recovery loss
 P_{QOSS} → Output Capacitance loss

Primary Switch Power Loss using GaN Power ICs:

$$P_{FET} = P_{COND} * k + P_{DIODE} + P_{T-ON} + P_{T-OFF} + P_{DR} + P_{QRR} + P_{QOSS}$$

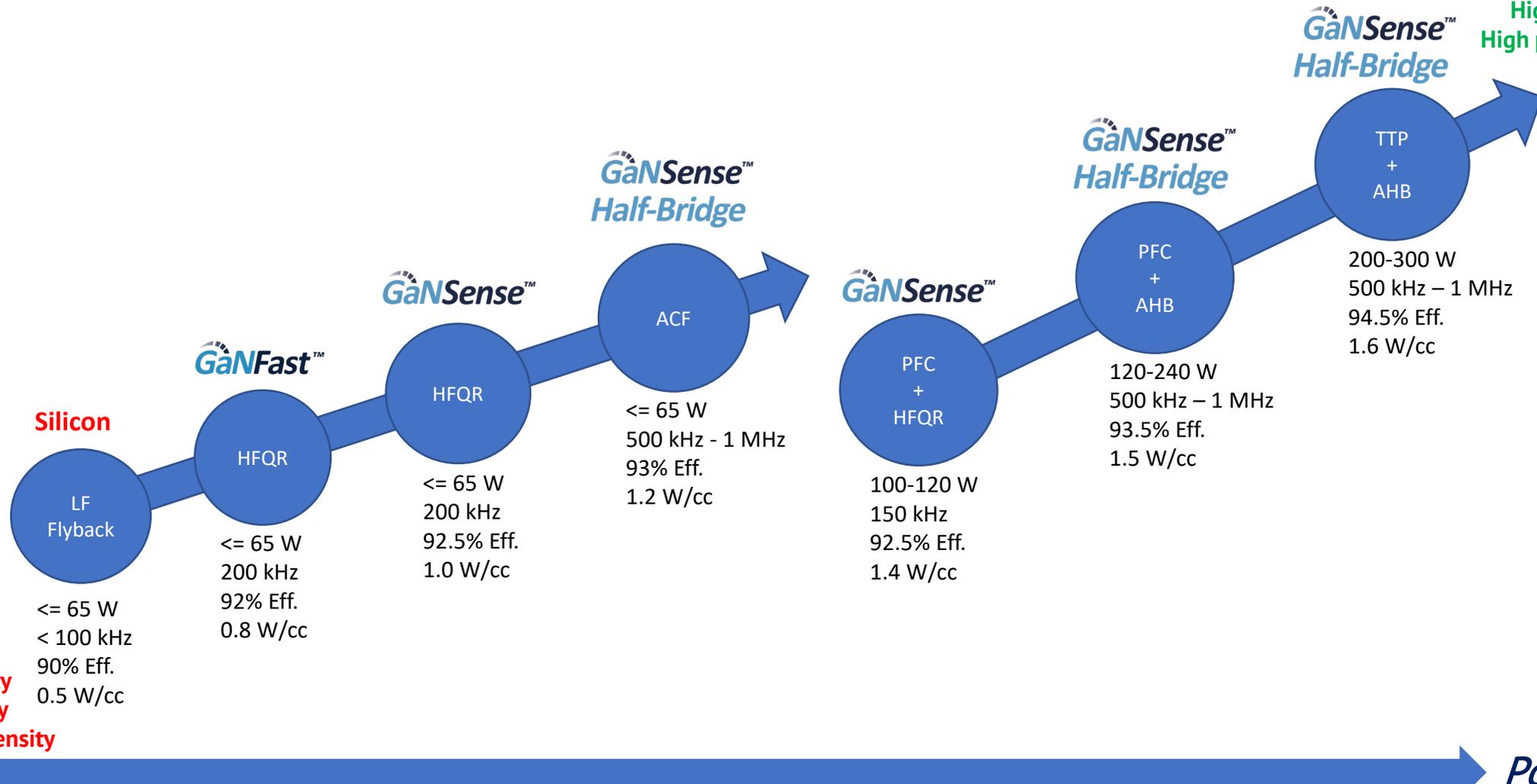
k → MINIMIZED
 P_{DIODE} → MINIMIZED
 P_{T-ON} → ELIMINATED
 P_{T-OFF} → ELIMINATED
 P_{DR} → ELIMINATED
 P_{QRR} → ELIMINATED
 P_{QOSS} → ELIMINATED

Soft-switching and GaN ICs **ELIMINATE** turn-on & reverse recovery losses & **MINIMIZE** drive, deadtime, and device charging losses

Enabling Next-Gen, High-Speed Topologies

Efficiency

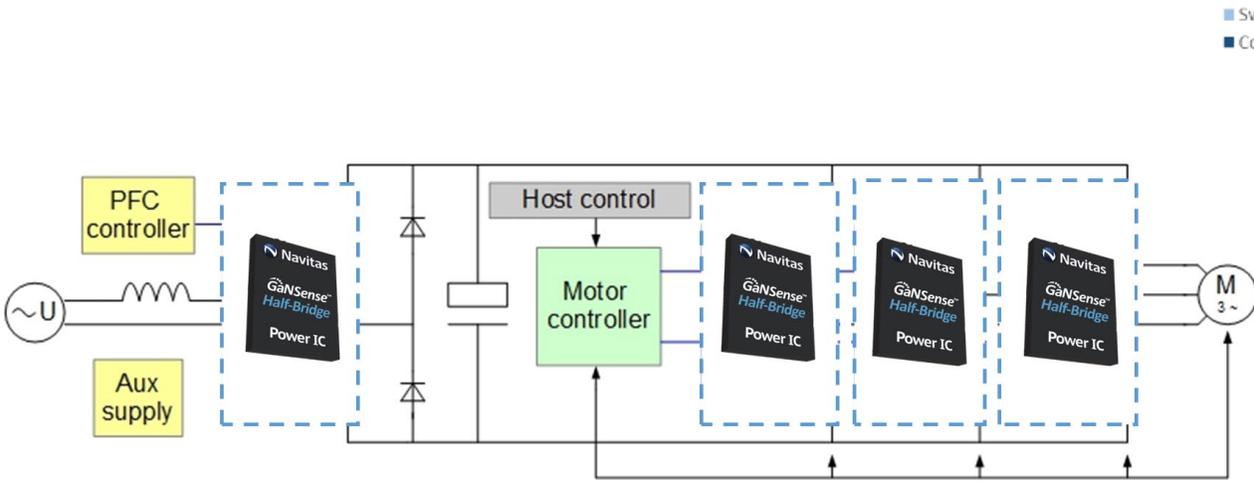
High frequency
High efficiency
High integration
High power density



Low frequency
Low efficiency
Low power density

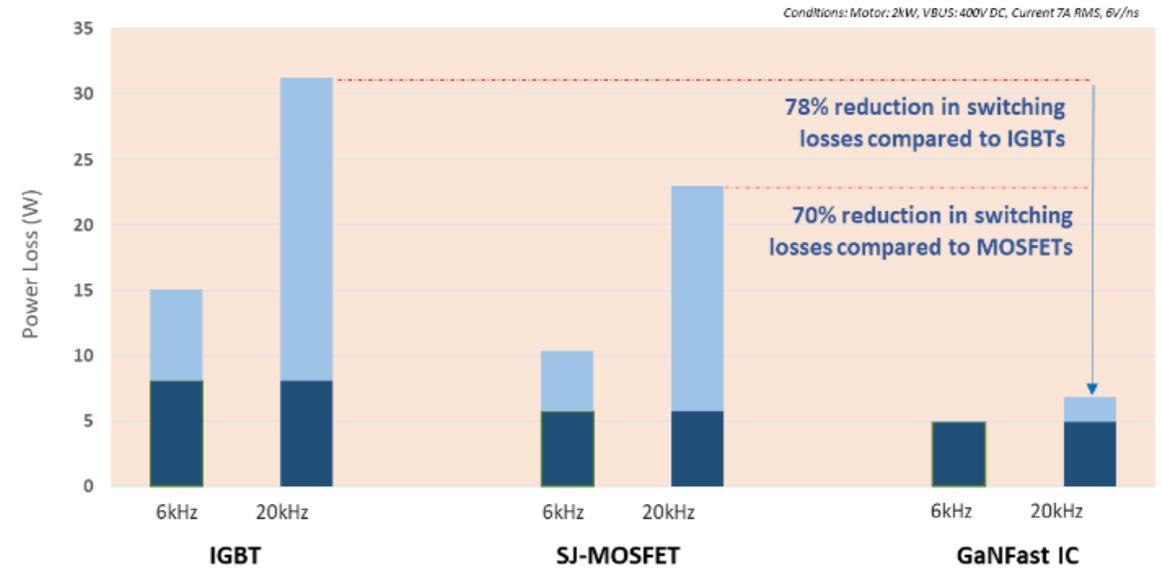
Power

GaN Sense Half-Bridge ICs Enable Inverter Motor Integration



■ Switching Losses
■ Conduction Losses

Power Loss Comparison between IGBT, SJ-MOSFET, and GaNFast IC in Motor Drives



- **Motor Drive:** compact, high efficiency, reduced thermal management
- **TTP PFC:** highest efficiency, fewest components and smallest footprint
- **Aux Supply:** compact, efficient HFQR topology

- Significant reduction in cost, weight and size of thermal management (heatsink, fans, etc.)
- GaN Power ICs into a 2kW motor drive
 - Inverter efficiency increases 2.5% (96%→ 98.5%)
 - Total losses reduced 50% (15W→6.8W)

Integrating drive, protection, and loss-less current sensing, provides compact, easy to design, robust systems

Complete integration of Half-Bridge phase into a single IC provides the most compact, efficient, fastest-switching, reliable and simplest solution for a wide variety of motor applications, such as fans, pumps, blowers, and compressors

	Discrete IGBT (Baseline)	Discrete (SJ) MOSFET	Discrete SiC	IPM (Gate Driver + 6 Switches)	Discrete GaN (Standalone)	Discrete GaN (Cascode)	GaNFast™ with GaNSense™
Electrical Efficiency	0	+	++	0	+++	++	+++
System Size (e.g. heatsink)	0	0	+	+	++	++	+++
Number of Components	0	0	0	++	-	0	++
Design Effort and Time	0	0	0	++	-	0	+++
Inverter Robustness	0	0	-	+	-	-	++
Inverter Reliability	0	0	+	+	+	0	++
System Cost	0	0	+	+	++	+	+++

- Navitas' mission is to Electrify the World to create a more sustainable future.
- Next-gen WBG (GaN and SiC) offer superior performance, and significantly lower CO₂ footprint in device and system manufacturing.
- Monolithic integration of driver and power stages enabled GaNFast power ICs to establish new benchmarks in efficiency, density, and reliability and lead the GaN market.
- GaNSense technology delivers new capability to integrate many useful drive, sensing, protection and autonomous control features.
- Complete integration of GaNSense Half-Bridge with additional sensing, monitoring, and protection delivers exceptional and cost-effective performance in the major power converter and inverter applications.
- It is time for legacy silicon to step to the side, as wide band gap is ready to take over.

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Electrify Our World™

